## DESIGNED <br> EXCLUSIVELY FOR SURFACE MOUNTING

SMT TL Series switches incorporate many desireable features that include:

- Tape \& reel packaging

This type of packaging is recommended for:

- economy
- suitability for automated placement
- handling of large quantities of components per packaging unit
- positive component positioning
- protection of terminals against damage during handling
- high static resistance
- Reflow solderable
- High temperature plastic materials
- Tin plated grounding brackets
- Tin-lead alloy over nickel terminal plating
- Terminals turned outward to prevent the shadow effect in infrared soldering and to permit visual inspection of the solder joints
- .021" ( 0.55 mm ) air gap between p.c. board and switch case
- End stackable with .400 " ( 10.16 mm ) pitch
- Available with positioning pins to assure correct switch orientation during the reflow process and provide additional mechanical integrity
- Protected against electrostatic discharges (ESD) up to 10 KV .
- Washable

Switches are designed to withstand cleaning processes, including hot water under pressure.

Surface mount devices (SMD) are subject to more stringent constraints of temperature, solderability, sealing and space savings than through-hole components.

To meet these requirements, APEM has designed a family of tiny surface mount switches that include TP Series pushbutton switches, TG Series slide switches and TL Series toggle switches. See Pushbutton \& Slide switch sections of catalog for TP \& TG Series respectively.


## ELECTRICAL SPECIFICATIONS

Contact ratings (resistive Ids.): 0.4 VA at 20 V max. (AC or DC) Minimum load:

10 mA at 50 mV or $10 \mu \mathrm{~A}$ at 5 VD
Initial contact resistance: $\quad 20$ milliohms maximum
Insulation resistance: $\quad 1000 \mathrm{M} \Omega \mathrm{min}$. at 500 VDC
Dielectric strength:
Electrical life (at full load): 2 position switches: 60,000 cycles
3 position switches: 30,000 cycles
Static resistance:
10 KV (Schaffner equipment)

## GENERAL SPECIFICATIONS

Operating temperature range: $-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$
Moisture resistance: 21 days per IEC 512-6 test 11c
Vibration resistance: $\quad 10-500 \mathrm{~Hz} / 10 \mathrm{~g}$ per IEC $512-4$ test 6 d
Shock resistance:
50 g per IEC 512-4 test 6c

## MATERIALS

Case:
Actuator:

Grounding brackets:
Contacts:
Terminals:

High temperature plastic UL94V-0
Nickel plated brass with high temperature plastic UL94V-0 cap
Tin plated steel (includes positioning pins)
Gold plated brass
Brass with tin-lead alloy over nickel plate

## SOLDERING AND CLEANING

Reflow soldering:
Infrared, vapor phase and infrared convection
Washable:
Per IEA-RS448-2: water and detergent preferred. Solvents.


Single pole toggle switches


| MODEL NO. | CIRCUIT |  |  |
| :--- | :--- | :--- | :--- |
| TL36WS84000 | ON | - | ON |
| TL39WS84000 | ON | OFF | ON |
| TL37WS84000 | MOM | OFF | MOM |
| TL38WS84000 | ON | OFF | MOM |
| TL32WS84000 | ON | - | MOM |
| Handle position: | III | II | I |



Single pole toggle switches with positioning pins


| SWITCH ACTION | P.C. BOARD DIMENSIONS |
| :---: | :---: |
| ON - ON Model shown |  |

## REFLOW SOLDERING - STANDARD PROFILE

The printed circuit board, carried by a conveyor belt, travels through the reflow soldering oven and experiences the following programmed cycles:
a. pre-heat to a maximum of $200^{\circ} \mathrm{C}$ for 30 seconds
b. reflow at a maximum of $245^{\circ} \mathrm{C}$ for 10 seconds
c. final cleaning

TEMPERATURE/TIME PROFILE (typical)


## P.C. BOARD REWORK RECOMMENDATIONS

Hot air reflow technique is preferred. Avoid the use of a soldering iron.

Caution: Excessive and/or repeated high temperature exposure may affect switch performance \& reliability.


PROCESSING STEPS


Component placement


Reflow soldering


Final
cleaning


